

NOTES

1. MATERIAL:  
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK  
TERMINALS - COPPER ALLOY
2. PLATING (SEE TABLE):  
CONTACT AREA - 0.38 MICROMETER MINIMUM GOLD OVER NICKEL  
SOLDER FOOT AREA - 2.54 MICROMETER MINIMUM TIN OVER NICKEL
3. PLATING (SEE TABLE):  
CONTACT AREA - 0.76 MICROMETER MINIMUM GOLD OVER NICKEL  
SOLDER AREA - 2.54 MICROMETER MINIMUM TIN OVER NICKEL
4. PLATING (SEE TABLE):  
CONTACT AREA - 0.76 MICROMETER MINIMUM GOLD OVER NICKEL, LUBRICATED  
SOLDER AREA: GOLD FLASH OVER NICKEL
5. PLATING (SEE TABLE):  
CONTACT AREA - 0.76 MICROMETER MINIMUM GOLD OVER 2.54 NICKEL  
SOLDER AREA: GOLD FLASH OVER NICKEL.
6. PLATING (SEE TABLE):  
CONTACT AREA - 0.38 MICROMETER MINIMUM GOLD OVER NICKEL,  
SOLDER AREA: GOLD FLASH OVER NICKEL.
7. SOLDER FEET COPLANAR WITHIN 0.10/0.04 FOR 20, 30 AND 40 CIRCUIT CONNECTORS,  
WITHIN 0.15/0.06 FOR 50 AND 70 CIRCUIT CONNECTORS
8. \* CONTACT PLANT FOR MORE INFORMATION
9. DATE CODE: 4 DIGIT (3 DIGIT DAY, 1 DIGIT YEAR)
10. THE CIRCUIT 1 IN